

## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-400	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-400	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-0.5	A
Peak Pulse Current	I <sub>CM</sub>	-1	A
Base Current	I <sub>B</sub>	-250	mA

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

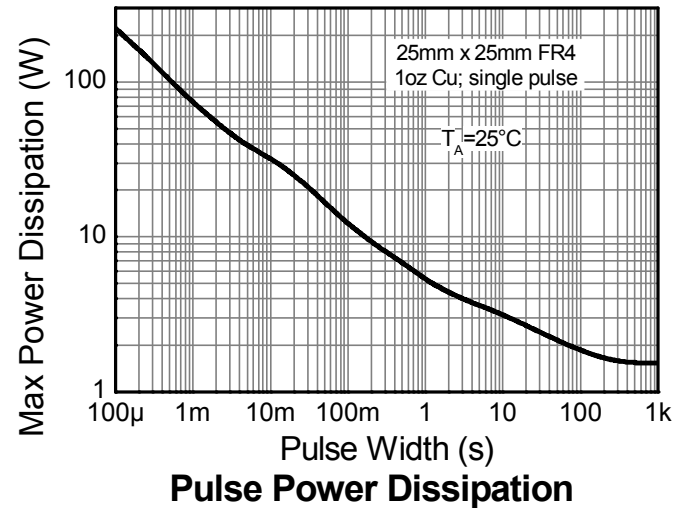
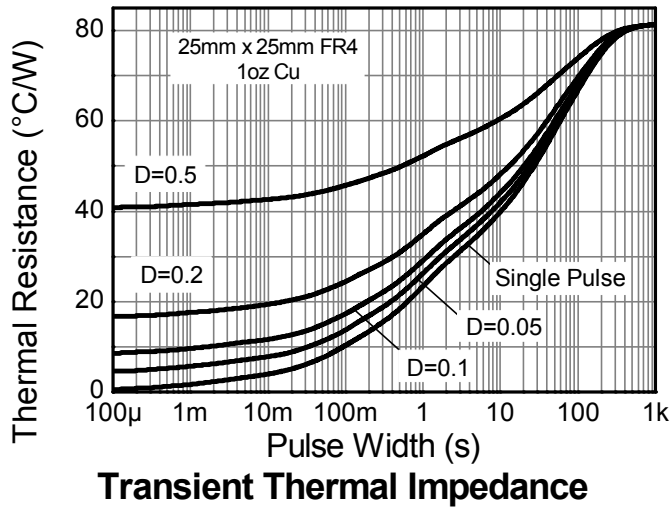
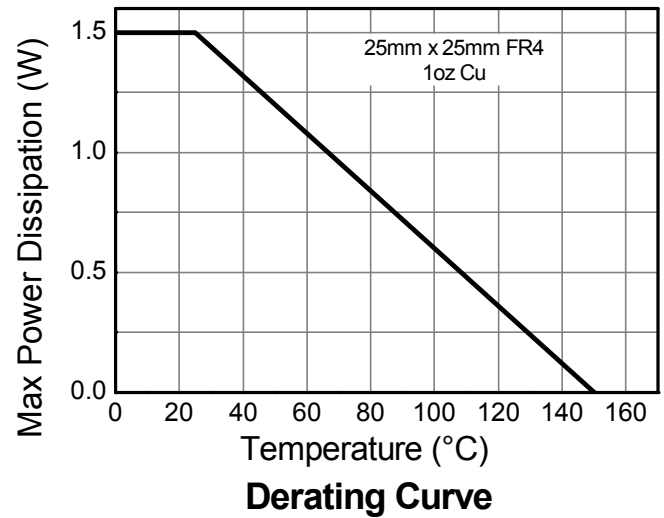
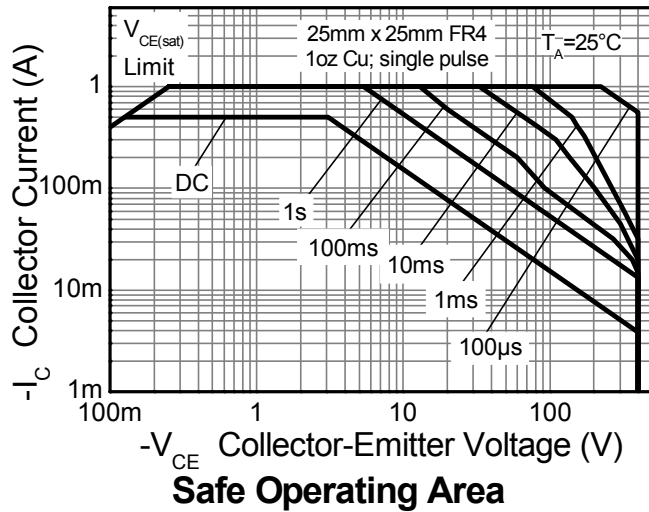
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	83	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	10.4	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with the exposed collector pad on 25mm x 25mm 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  - Thermal resistance from junction to solder-point (on the exposed collector pad).
  - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## Thermal Characteristics and Derating information

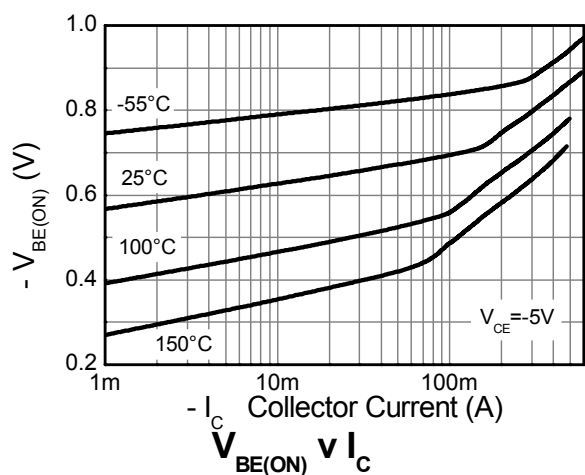
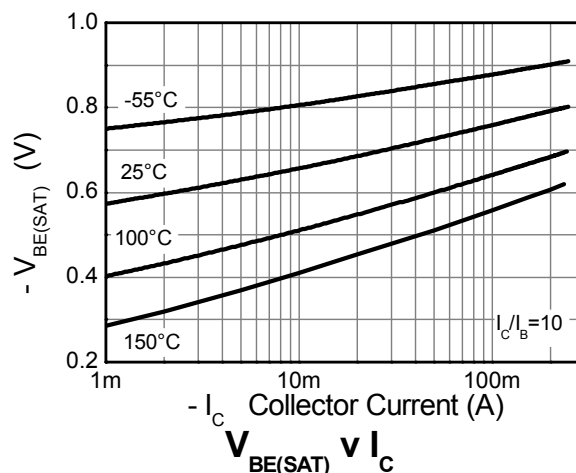
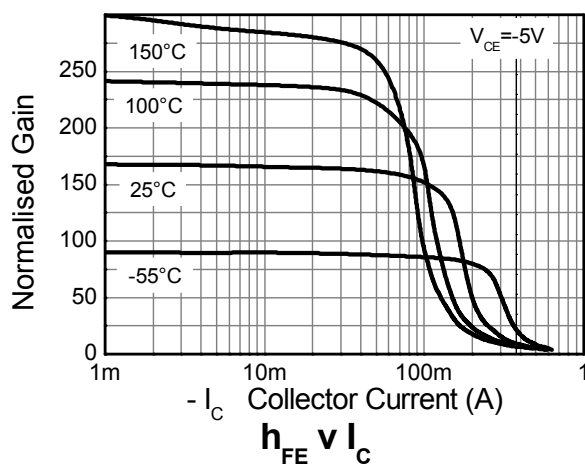
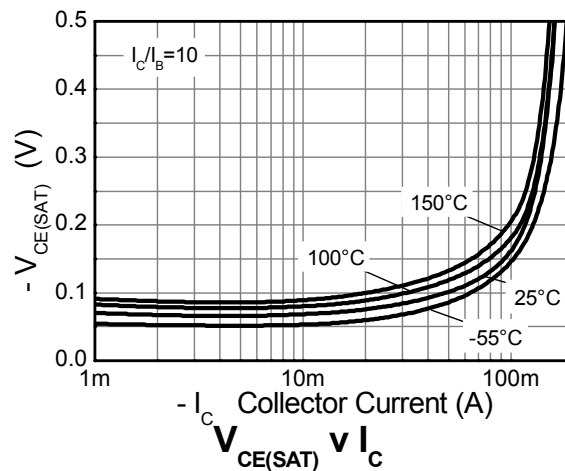
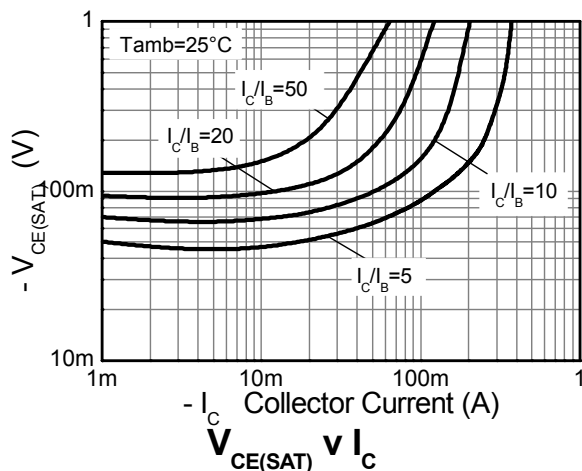


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-400	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-400	-	-	V	I <sub>C</sub> = -1mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-	-	V	I <sub>E</sub> = -100μA
Collector-Emitter Cut-off Current	I <sub>CES</sub>	-	-	-100	nA	V <sub>CE</sub> = -320V
Collector Cut-off Current	I <sub>CBO</sub>	-	-	-100	nA	V <sub>CB</sub> = -320V
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-100	nA	V <sub>EB</sub> = -6V
Static Forward Current Transfer Ratio (Note 8)	h <sub>FE</sub>	140 140	-	450 400	-	I <sub>C</sub> = -20mA, V <sub>CE</sub> = -5V I <sub>C</sub> = -100mA, V <sub>CE</sub> = -5V
Collector-Emitter saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	-	-	-250 -400	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA I <sub>C</sub> = -200mA, I <sub>B</sub> = -40mA
Base-Emitter saturation Voltage (Note 8)	V <sub>BE(sat)</sub>	-	-0.75	-0.9	V	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Base-Emitter Turn-On Current (Note 8)	V <sub>BE(on)</sub>	-	-	-0.8	V	I <sub>C</sub> = -200mA, V <sub>CE</sub> = -10V
Transition frequency	f <sub>T</sub>	-	75	-	MHz	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -5V, f = 50MHz
Collector Output Capacitance	C <sub>obo</sub>	-	19	-	pF	V <sub>CB</sub> = -10V, I <sub>E</sub> = 0, f = 1MHz
Delay Time	t <sub>(d)</sub>	-	89	-	ns	V <sub>CC</sub> = -200V, I <sub>C</sub> = -100mA, I <sub>B1</sub> = -10mA, I <sub>B2</sub> = 20mA
Rise Time	t <sub>(r)</sub>	-	111	-	ns	
Storage Time	t <sub>(s)</sub>	-	2165	-	ns	
Fall Time	t <sub>(f)</sub>	-	185	-	ns	

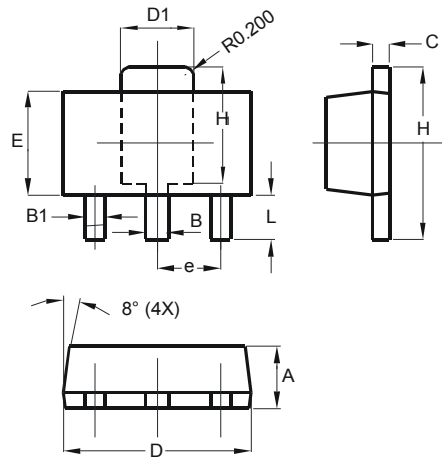
Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%

**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



## Package Outline Dimensions

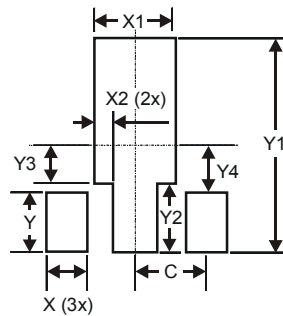
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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